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PATENT
10/31/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/917,127

Filed: July 27, 2001

For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING
WAFER LEVEL PROCESSING AND
DEVICES RESULTING
THEREFROM

Examiner: M. Trinh

Group Art Unit: 2822

Attorney Docket No.: 3572.1US (97-1243.1)

CERTIFICATE OF MAILING

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed July 19, 2002, the three-month shortened statutory period for response to which expires on October 21, 2002, October 19 being a Saturday.

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